

Model DA-750 / DS-750

Die Bonder / Sorter

DA-750 / DS-750

FEATURING:

- Pick & Place System with Rotary Pick-up Tool
- Capable to pick from Wafer or Tray
- Flip Chip capability
- Powerful Wafer Map processing software
- Up Looking Vision for post-pick alignment or inspection
- Flexible Output Configuration
- High Performance Cameras and Pattern Recognition System
- Wide range of dispensing options
- Programmable parameters for process and motion controls
- "Windows" based GUI user interface



DIAS
AUTOMATION

www.diasautomation.com

DA-750 / DS-750

BASIC SPECIFICATIONS:

- System performance

Die Size	20 - 800 mils (0.5 - 20 mm)
Placement Accuracy (XY)	+/- 1.6mil (+/-40 um) - XY (Standard) +/- 1.0mil (+/-25 um) -XY (with bottom CCTV)
Placement Accuracy (Theta)	+/- 1.5 deg (without bottom CCTV) +/- 0.25 deg (with bottom CCTV)

- Rotary Pick & Place Head

Angular Travel	+/- 150 deg
Maximum Z Travel	2.50" (64 mm)
Bond Force	30 -1000 gr

- Input Wafer Table

Wafer Size	Max. 8" (200 mm) dia. (Standard) Max. 12" (300 mm) dia. (Optional)
Waffle Trays	2" - 6" (50-150 mm)

- Output Module options

XY Table (for Substrate/Wafer/Trays)	up to 13.5" x8.0" (340x200mm)
SMEMA Conveyor (for Substrate/Carrier)	up to 12"x6" (300x150mm)
Tape &-Reel Handler	8 - 56 mm wide

- User Interface

Display Screen	Dual 15" SVGA Color LCD
Input Device	PC Track Ball and Keypad
Permanent Storages	Min. 80 GB HDD

- Software

Operating Platform	MS Windows
External Map Input	Capable to process industry most common formats
Video Processing	256 Grey Scale, 1/4 Pixel accuracy

- Utility, Size and Weight

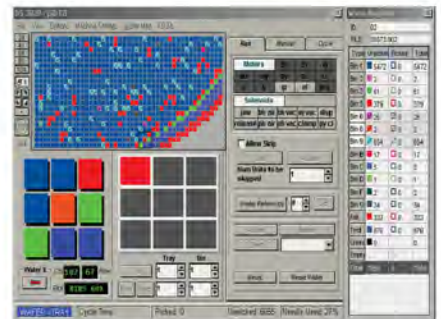
Power	220V/110V, 2000 Watts
Compressed Air	70 PSI
Physical dimension	48"(W)x54"(D)x65"(H) 1219mm(W)x1372mm(D)x1650mm(H)
Weight	1200 Kg

OPTIONAL MODULES

Epoxy Dispensing System	Transfer Stamp from a Rotary Reservoir Precision Time-Pressure Controlled Needles Precision Pen Writing Needle
Bottom View CCTV	with Zoom Lens and Back Lite
Automatic Wafer Loader	to auto-load Wafer or Tray Carrier from/to Magazine
Output Tape & Reel Handler	for Sorting to Tape Carrier
Multi Magazine Handler	to auto-load Strip Carrier from/to Magazine
Reel to Reel Handler	for auto-feed Tape product / Tape Carrier
Post-pick Die Flipper	for Flip Chip application



Rotary P&P Head and bottom view CCTV



GUI Display of Menu and Map



Wafer to Tray Sorter

Headquarters & Factory

DIAS Automation (HK) Ltd.

Unit 7-8, 3/F, Block A, Merit Industrial Bldg.,
94 Tokwawan Road, Kowloon, Hong Kong
Tel. : (852) 2333-3213, 2333-6298
Fax : (852) 2356-2860, 2764-0187
Email : sales@diasautomation.com

DIAS
AUTOMATION
www.diasautomation.com